



FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #16602

Generic Copy

Issue Date: 11-May-2011

TITLE: Qualification of UTAC, Bangkok, Thailand for Assembly/Test of PDIP7/8 LD

PROPOSED FIRST SHIP DATE: 11-Aug-2011

AFFECTED CHANGE CATEGORY(S): Subcontractor Assembly/Test Location

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact your local ON Semiconductor Sales Office or <Scott.Brow@onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Office

ADDITIONAL RELIABILITY DATA: Available

Contact your local ON Semiconductor Sales Office or <Ken.Fergus@onsemi.com>

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>.

DESCRIPTION AND PURPOSE:

This is the Final Product Change Notice to alert customers of the planned qualification of UTAC, Bangkok, Thailand, to assemble and test products in PDIP7/8 lead packages. UTAC will provide additional capacity to supplement ON Semiconductors' current assembly and test facility located at Unisem, Batam, Indonesia. UTAC is a currently qualified for assembly/test to run PDIP8 lead packages within ON Semiconductor. These UTAC PDIP devices are RoHs and HF compliant.

**FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #16602****RELIABILITY DATA SUMMARY:**

As there is no change in the bill of materials (BOM) from the products already qualified at UTAC, the products will qualify by similarity to devices already running in production.

<u>Reliability Summary:</u>		Lot 1	Lot 2	Lot 3
Autoclave	121C/15PSI/100%RH/240 Hrs	0/116	0/116	0/116
Temperature Cycle	-65C/+150C, 500 Cycle	0/121	0/121	0/121
THB	85C/85% RH/1000hrs	0/116	0/116	0/116
Wire Bond Inspection	100-500X	0/5	0/5	0/5
Wire Pull		0/5	0/5	0/5

ELECTRICAL CHARACTERISTIC SUMMARY:

Datasheet specifications will remain unchanged, and data is available upon request.

CHANGED PART IDENTIFICATION:

Devices assembled by UTL will include the character 'G' as the identifier in the trace code. Upon expiration of the PCN devices may be sourced from either UTL, or previously qualified assembly locations. Manufacturing traceability will be maintained to allow identification of the assembly source.

As per JESD97, May 2004, section 5 the following information will be included to indicate the appropriate Pb-free 2nd level interconnect:

- Package labeling for material assembled in UTL will state 'e4', to indicate the use of precious metals, no Sn
- Package labeling for material assembled in previously qualified assembly locations will state 'e3' to indicate the use of Sn.



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List of affected General Parts:

PART

NCP1203P100G
NCP1203P60G
NCP1203P40G
NCP1200P60G
NCP1200P100G
NCP1200P40G
NCP1207APG